FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #20133A

Generic Copy

Issue Date: 19-Dec-2013

TITLE: Material Change on Leadframe and Mold resin of SOIC8 as to Flash memory LE25U40CMC series.

PROPOSED FIRST SHIP DATE: 19-Mar-2014

AFFECTED CHANGE CATEGORY(S): Material of Leadframe and Mold resin

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or
<Hiroshi.Motegi@onsemi.com> or <Yujiro.Yoshida@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office or <Takashi.Asami@onsemi.com>

ADDITIONAL RELIABILITY DATA: Available
Contact your local ON Semiconductor Sales Office or <Yukihisa Iizuka@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

The purpose of this change is to increase the units in the Leadframe for enhancement of the manufacturing process with greater efficiency & productivity. The Mold resin is changed at the same time.

The package outline dimension has no change. And the characteristic and quality also will have no impact.

In addition, there are no changes such as the mark on the package. This change can be traced by package marking lot number.

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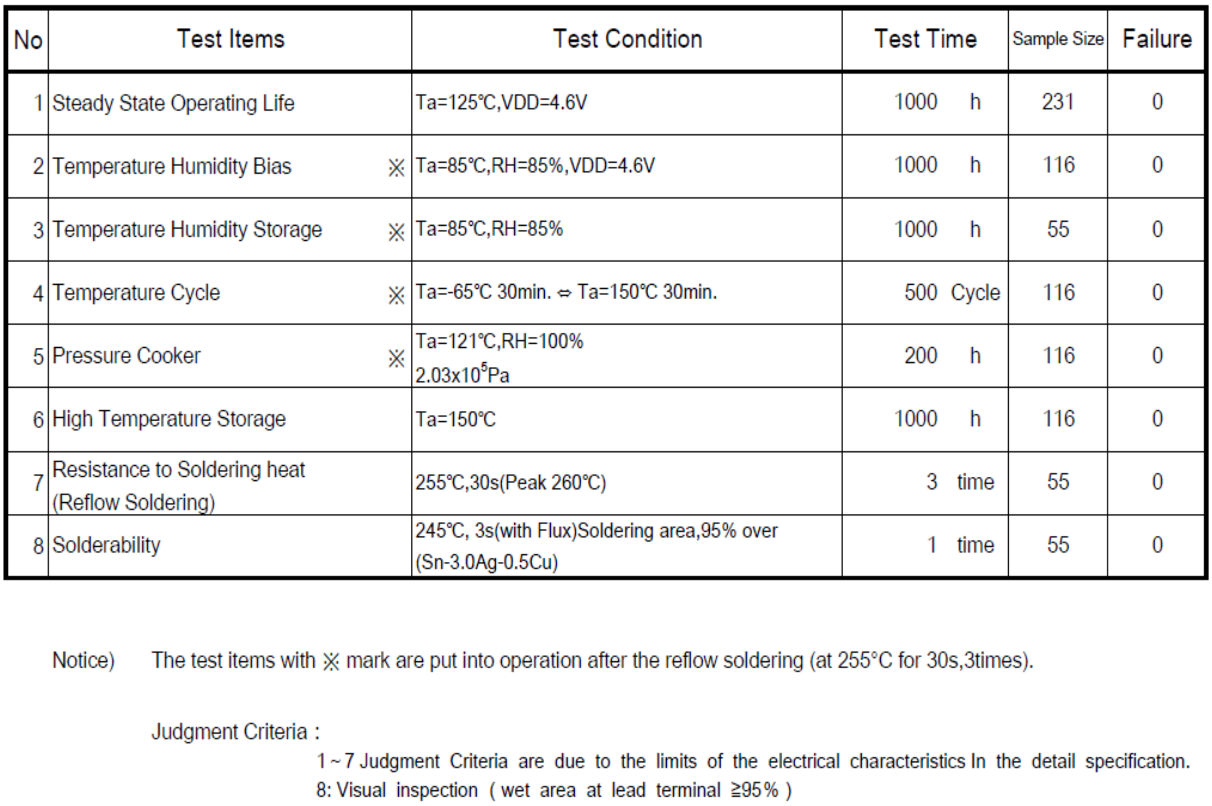
RELIABILITY DATA SUMMARY:

Reliability Test Results:



No	Test Items		Test Condition	Test Time		Sample Size	Failure
1	Steady State Operating Life		Ta=125℃,VDD=4.6V	1000	h	231	0
2	Temperature Humidity Bias	※	Ta=85℃,RH=85%,VDD=4.6V	1000	h	116	0
3	Temperature Humidity Storage	※	Ta=85℃,RH=85%	1000	h	55	0
4	Temperature Cycle	※	Ta=-65℃ 30min. ⇔ Ta=150℃ 30min.	500	Cycle	116	0
5	Pressure Cooker	※	Ta=121℃,RH=100% $2.03x10^5$Pa	200	h	116	0
6	High Temperature Storage		Ta=150℃	1000	h	116	0
7	Resistance to Soldering heat (Reflow Soldering)		255℃,30s(Peak 260℃)	3	time	55	0
8	Solderability		245℃, 3s(with Flux)Soldering area,95% over (Sn-3.0Ag-0.5Cu)	1	time	55	0

Notice) The test items with ※ mark are put into operation after the reflow soldering (at 255°C for 30s,3times).

Judgment Criteria :

1 ~ 7 Judgment Criteria are due to the limits of the electrical characteristics In the detail specification.
8: Visual inspection (wet area at lead terminal ≧95%)

ELECTRICAL CHARACTERISTIC SUMMARY:

This package material change doesn’t have the impact to electrical characteristics.

CHANGED PART IDENTIFICATION:

This change can be identified by marking lot number.

List of affected General Parts:

LE25U40CMC-AH